



Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.SolderMask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
Front.Cu	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1 mm	FR4 natural	4.5	0.02
In1.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.24 mm	FR4 natural	4.5	0.02
In2.Cu	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1 mm	FR4 natural	4.5	0.02
Back.Cu	copper		0.035 mm		1	0
B.SolderMask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1,6000 mm
Board overall dimensions:	97,0000 mm x 37,5000 mm		
Min track/spacing:	0,0900 mm / 0,0900 mm	Min hole diameter:	0,1000 mm
Copper Finish:	HAL lead-free	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		